EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	jp-2001239395-$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/15 14:49
S2	2	("5849606").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/15 15:35
S3	2	("5128746").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/15 14:54
S4	2167	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:03
S5	31184	228/179.1,180.21-22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:03
S6	3239	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:04
S7	39	(S4 or S6) and (reinforc$4 near10 (epoxy or resin)) and (PCB or board or substrate) same paste same (bond$4 or solder$3 or join$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:06
S8	1168	mori-masato.in. or onishi-hiroaki.in. or hirano-masato.in. or nishida-kazuto.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:09

S9	5	S8 and (reinforc$4 near10 (epoxy or resin)) and (PCB or board or substrate) same paste same (bond $4 or solder$3 or join$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:10
S10	5	S8 and (reinforc$4 near10 (epoxy or resin)) and (PCB or board or substrate) same3 paste same3 (bond $4 or solder$3 or join$3) same3 (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:16
S11	9	S8 and (reinforc$4 near10 (epoxy or resin)) and (PCB or board or substrate) same (bond$4 or solder $3 or join$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:17
S12	173	(S4 or S6) and (reinforc$4 near10 (epoxy or resin)) and (PCB or board or substrate) same (bond$4 or solder $3 or join$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S13	134	S12 not S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S14	104	S13 and @ad<"20040224"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S15	117	("4448847" | "4604644" | "4855001" | "4980086").PN. OR ("5128746").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 15:31
S16	107	S15 and @ad<"20040224"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 15:31
S17	9	S16 and (reinforc$4 near10 (epoxy or resin)) and (PCB or board or substrate) and (bond$4 or solder$3 or join$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:32
S19	5	(S4 or S6 or S8) and (reinforc$4 near10 (epoxy or resin)) near10 (appl$4 or deposit$3 or suppl$4 or form$3 of fill$3) near10 paste and (substrate or board or PCB)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:51

S20	30	("3339274" | "3959874" | "4172907" | "4616406" | "5120678" | "5148266" | "5155904" | "5241133" | "5316788" | "5397917" | "5433822" | "5436203" | "5468681" | "5581122" | "5663106" | "5663593" | "5798563" | "5824569" | "5889655" | "6229209").PN. OR ("6365499"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:06
S21	2	ishidoya.in. and resin and substrate and paste and solder$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 16:10
S22	4	ishidoya.in. and resin and paste and solder$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 16:11
S23	10	("5128746" | "5985043" | "5985456" | "5985486" | "6458472").PN. OR ("6667194"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:26
S24	17	("20010003058" | "20020167077" | "20030080437" | "20030096452" | "5975408" | "6458472" | "6475828" | "6660560" | "6667194").PN. OR ("6773958").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:29
S25	2167	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S26	3239	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S27	4	(S25 or S26) and resin and print$3 near5 paste near10 (board or substrate) same2 (retain$4 or keep $3 or maintain$3 or preserv$3) near5 (shap$3 or form or pattern or configuration)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S28	2	("6867503").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/17 12:19

S29	0	wo-2002076161-$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 11:53
S30	1	wo-02076161-$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 11:53
S31	320	print$3 near5 paste near5 (adhesive or resin or flux) same (board or substrate) and (bond$3 or join$3 or solder$3) near5 component$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 13:32
S32	210	print$3 near5 paste near5 (adhesive or resin) same (board or substrate) and (bond$3 or join$3 or solder$3) near5 component$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 13:32
S33	64	print$3 near5 paste near5 (adhesive or resin) same (board or substrate) same (bond$3 or join$3 or solder$3) near5 component$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 13:33
S34	8	(bond$3 or join$3) near5 component$1 same (board or substrate) and both near5 (bump$1 or ball$1) near5 paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:34
S35	2	(bond$3 or join$3) near5 component$1 same (board or substrate) and (benefit or advantage) near5 (bump$1 or ball$1) near5 paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:38
S36	17	(bond$3 or join$3) near5 component$1 same (board or substrate) and (benefit or advantage) same (bump$1 or ball$1) near5 paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:38
S37	40	(deposit$3 or print$3) near5 paste near5 (adhesive or resin) same (bump$1 or ball$1) and (bond$3 or join$3 or solder$3) near5 component$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:57

S38	11	$3coat$3 near5 paste near5 (bump $1 or ball$1) same (adhesive or resin) and (bond$3 or join$3 or solder$3) near5 component$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 18:31
S39	69	(deposit$3 or print$3) near5 paste near5 (adhesive or resin) near5 (layer or preform) and (bond$3 or join$3 or solder$3) near5 component $1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 18:37
S40	10	(paste near5 (mix$3 or flow$3 or melt$3) near5 resin) same (interconnect$3 or join$3 or bond $3) same bump$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 10:26
S41	0	jp-200414964-$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 10:49
S42	2	jp-2004014964-$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 10:49
S43	2422	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 13:09
S44	3299	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 13:09
S45	146	(S43 or S44) and (resin same (preform$1 or sheet or layer) same paste) and (bond$3 or join$3 or solder$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 13:09
S46	832	(S43 or S44) and ((bump$1 or ball $1) same paste) same (bond$3 or join$3 or solder$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 14:00

| S47 | 341 | (S43 or S44) and (bump$1 near10 paste) same (bond$3 or join$3 or solder$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/10/09 14:01 |

EAST Search History (Interference)

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10/9/2009 4:10:48 PM
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